

## TAB BONDING MACHINE TM-300PR-MKIII



### **OVERVIEW**

Specifically designed for fine pitch TAB Bonding, TM-300PR-MKIII is equipped with a high accuracy microprocessor based pulse heat controller that allows better temperature control and repeatability needed for fine pitch TAB Bonding process.

The integrated **Intelli-Pulse** system offers high speed and accurate temperature control with easy usage as system parameters are automatically adjusted. The ergonomically designed bottom vision camera system is capable of fine pitch alignment and allows users to enhance ITO and TAB conductive lines clarity. The integration of co-planarity mechanism provides adjustment of bonding head to substrates enables evenly distributed pressure across the bondline. Maximum output can be achieved with the rotary table that allow user to simultaneously load and unload the substrates during the bonding process.

## TAB BONDING MACHINE TM-300PR-MKIII

### FEATURES & BENEFITS

- High accuracy microprocessor based pulse heat controller
- Dual Bonding pressure
- 4 stage ramp temperature
- **Intelli-Pulse** system offers fast and accurate temperature control as system parameters are automatically adjusted
- Real time temperature profile display on LCD touch panel
- Bottom vision camera system and 2 CCD system for direct viewing
- Electronics pressure control for precision bonding force output
- Leveling mechanism adjustment on press assembly

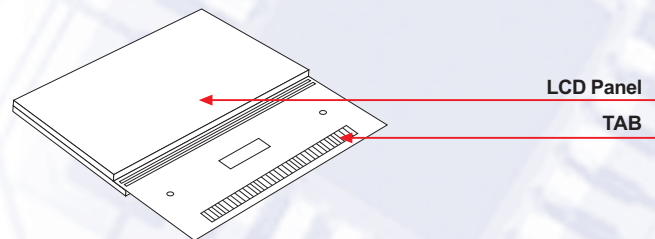
- Electronic pressure control with digital display
- Built-in vacuum
- Manual mode for machine set-up
- Dual thermocouple ensures over temperature protection
- 20 programmable profiles can be stored electronically
- LCD touch screen controller for easy programming, storing and recalling parameter settings
- User pre-set password

### APPLICATIONS

- ACF Bonding of TAB to LCD
- ACF Bonding of Flex Printed Circuit to LCD

### OPTIONS

- Connection to load cell controller (TM-29S) for measurement of bonding force
- Temperature profiling and programming software
- Color CCD system

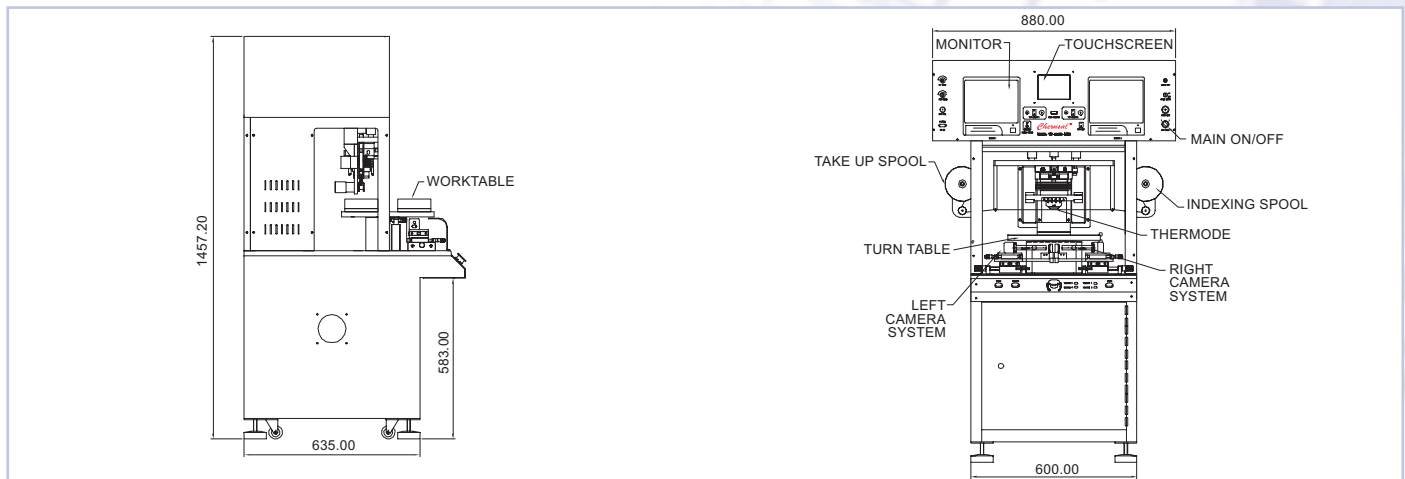


### SPECIFICATIONS

Heating Method	Pulse Heat
Power Requirement	220VAC10% Free from momentary surge and failure
Supply Pressure	Filtered clean air, 5-7 kgf / cm <sup>2</sup>
Programme Profiles	20
Visual Aid	2 units of Colour or B/W CCD system
Magnification	230x
LCD Size	120mm x 90mm
Work Table Size	120mm x 120mm
Work Area	420mm x 420mm
Dimensions	880mm (L) x 800mm (W) x 1460mm (H)
Weight	212kg

Pulse Heating Specifications	
Temperature Ramp Profile	4 stages
Start Temp.	30°C to 300°C
Ramp Temp	30°C to 450°C
Release Temp	30°C to 450°C
Hold Period	1 to 100 seconds
Ramp Period	1 to 25 seconds
Thermode Specifications	
Bonding Force	3.5kgf – 70kgf
Max. Thermode Size	10mm x 2mm(min) to 75mm x 2mm(max)
Thermocouple Type	K Type

Specifications are subjected to change without prior notice



### HEADQUARTER (SINGAPORE)



#### TRIMECH TECHNOLOGY PTE LTD

A member of TRIMECH group of companies

No. 70 Ubi Crescent #01-02/03

Ubi Techpark

Singapore 408570

Tel : 65 6741 0346

Fax: 65 6741 7850

Email:sales@cherusal.com

Website: www.cherusal.com



Certificate No: 651176

### REGIONAL OFFICES

#### • Beijing

Tel: (86) 10 6566 2172

Fax: (86) 10 6566 2171

Email: james-zj\_yao@cherusal.com

#### • Hong Kong

Tel: (852) 2111 0982

Fax: (852) 2111 0983

Email: bs\_tan@cherusal.com

#### • Shenzhen

Tel: (86) 755 8231 8767

Fax: (86) 755 8231 8763

Email: bs\_tan@cherusal.com

#### • Shanghai

Tel: (86) 21 5055 1008 ext 16

Fax: (86) 21 5834 6323

Email: james-zj\_yao@cherusal.com

#### • Taiwan

Tel: (886) 3 262 1188

Fax: (886) 3 262 0208

Email: kenny-tan@cherusal.com

#### • Thailand

Tel: (66) 2 690 2466

Fax: (66) 2 690 2467

Email: nipon\_k@cherusal.com